

IN THE SPECIFICATION

Please amend the Specification at page 12 as follows to add the serial number of the referred to application as follows. The specific amendment is identified in the attached Appendix by underlining.

B' --Trenches 506 are etched to process a wafer into individual devices (by etching into the substrate) or, in some cases, into appropriate groups of devices, for example, as shown in a commonly assigned application serial number 09/896,797 entitled Redundant Device Array filed concurrently herewith (and which is incorporated herein by reference) by etching into the substrate in some places while stopping the etch prior to it reaching the substrate in others.--

IN THE CLAIMS:

✓ Please cancel claims 1-3 and 13-17 and 19 without prejudice.

Please amend claims 4, 6, 9, 10 and 12 as follows so as to rewrite allowable claims 4, 9 and 10 in independent form by incorporating the limitations of each claim from which they depended and to add additional, alternative, dependencies to claim 6. The specific amendments to each claim are identified in the attached Appendix by underlining for additions and pairs of square brackets (“[“ and “]”) to indicate deletions.

B² 1. (Amended) A method of creating a hybridized chip combining a top active optical device chip, having a substrate including a first side and active device contacts on top active devices located on the first side, the top active optical devices also being on the first side, with an electronic chip having electronic chip contacts, when at least some of the active device contacts are not aligned with at least some of the electronic chip contacts when the top active optical